



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re U.S. Patent Application of

OSHIMA *et al.*

Application Number: 09/987,914

Filed: November 16, 2001

For: SEMICONDUCTOR DEVICE AND  
ITS FABRICATION METHOD

Attorney Docket No. HITA.0120

Honorable Assistant Commissioner  
for Patents  
Washington, D.C. 20231

Art Unit: 2823

Examiner:  
Brewster, William M.

RECEIVED  
MAR 13 2003  
TECHNOLOGY CENTER 2800

**RESPONSE AND AMENDMENT UNDER 37 C.F.R. §1.111**

Sir:

This is in response to the Office Action dated February 11, 2003, the shortened period for response to which will expire on March 11, 2003. Applicants hereby elect the continuing prosecution of Species I, drawn to a method of fabricating a semiconductor device having wirings formed in wiring grooves and a connection member formed integrally with the wirings in via holes for connecting the wirings and lower layer wirings thereof without traverse. Claims 18 through 27 pertain to the elected Species.